

PRE-RELEASE VERSION (FDIS)

**Semiconductor devices – Semiconductor devices for energy harvesting and generation –
Part 6: Test and evaluation methods for vertical contact mode triboelectric energy harvesting devices**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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TITLE:
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NOTE FROM TC/SC OFFICERS:

CONTENTS

FOREWORD	4
1 Scope	6
2 Normative references	6
3 Terms and definitions	6
3.1 General terms	6
3.2 Triboelectric transducer	7
3.3 Characteristic parameters	8
4 Essential ratings and characteristics	10
4.1 Identification and type	10
4.2 Limiting values and operating conditions	10
4.3 Additional information	10
5 Test method	10
5.1 General	10
5.2 Electrical characteristics	12
5.2.1 Test procedure	12
5.2.2 Open-circuit voltage	13
5.2.3 Short-circuit current	13
5.2.4 Output voltage	14
5.2.5 Output current	14
5.2.6 Output power	15
5.2.7 Optimal load impedance	15
5.2.8 Maximum output power	15
5.2.9 Stored charge	15
5.2.10 Capacitance	16
5.3 Mechanical characteristics	17
5.3.1 Test procedure	17
5.3.2 Contact area	17
5.3.3 Input force	18
5.3.4 Input frequency	19
5.3.5 Relative humidity range	19
5.3.6 Temperature range	20
Annex A (informative) Vertical contact modes	21
A.1 Double electrode mode	21
A.2 Single electrode mode	21
Annex B (informative) Test setup for vertical contact mode triboelectric energy harvester	22
B.1 Example of test setup and characterization	22
B.2 Experimental data	22
Bibliography	24
Figure 1 – Vertical contact mode triboelectric energy harvester	7
Figure 2 – Fundamental theories of four working modes of vertical contact mode triboelectric energy harvester	8
Figure 3 – Equivalent circuit of triboelectric energy harvester	9

Figure 4 – Measurement procedure of vertical contact mode triboelectric energy harvester	11
Figure 5 – Test setup for the electrical characteristics of vertical contact mode triboelectric energy harvester.....	12
Figure 6 – Instantaneous open-circuit output voltage characteristics	13
Figure 7 – Instantaneous short-circuit output current characteristics	14
Figure 8 – Output voltage and current of triboelectric energy harvester under different loads.....	14
Figure 9 – Output power of triboelectric energy harvester at various external loads	15
Figure 10 – Stored charging time relationship at different load capacitances of triboelectric energy harvester.....	16
Figure 11 – Capacitance between the two electrodes of a triboelectric energy harvester	16
Figure 12 – Block diagram of a test setup for evaluating the reliability of vertical contact mode triboelectric energy harvester	17
Figure 13 – Instantaneous open-circuit voltage characteristics for four different contact areas of contact mode triboelectric energy harvester	18
Figure 14 – Output voltage and current under different input forces on vertical contact mode triboelectric energy harvester	18
Figure 15 – Output voltage and current under different working frequencies on vertical contact mode triboelectric energy harvester	19
Figure 16 – Triboelectric output voltage as a function of relative humidity	20
Figure 17 – Open-circuit voltage of triboelectric energy harvester at different temperatures	20
Figure A.1 – Operation mode of vertical contact mode triboelectric energy harvester.....	21
Figure B.1 – Measurement setup for vertical contact mode triboelectric energy harvester	22
Figure B.2 – Electrical characterization results of the pressure-voltage relationship.....	23
Table 1 – Specification parameters for vertical contact mode triboelectric energy harvester	10

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – SEMICONDUCTOR DEVICES FOR ENERGY HARVESTING AND GENERATION –

Part 6: Test and evaluation methods for vertical contact mode triboelectric energy harvesting devices

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62830 series, published under the general title *Semiconductor devices – Semiconductor devices for energy harvesting and generation*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

SEMICONDUCTOR DEVICES – SEMICONDUCTOR DEVICES FOR ENERGY HARVESTING AND GENERATION –

Part 6: Test and evaluation methods for vertical contact mode triboelectric energy harvesting devices

1 Scope

This part of IEC 62830 defines terms, definitions, symbols, and specifies configurations and test methods to be used to evaluate and determine the performance characteristics of vertical contact mode triboelectric energy harvesting devices for practical use. This document is applicable to energy harvesting devices as power sources for wearable devices and wireless sensors used in healthcare monitoring, consumer electronics, general industries, military and aerospace applications without any limitations on device technology and size.

2 Normative references

There are no normative references in this document.